MC74LVX245

Octal Bus Transceiver

With 5 V−Tolerant Inputs

The MC74LVX245 is an advanced high speed CMOS octal bus transceiver.

It is intended for two−way asynchronous communication between data buses. The direction of data transmission is determined by the level of the T/$\overline{R}$ input. The output enable pin ($\overline{OE}$) can be used to disable the device, so that the buses are effectively isolated.

All inputs are equipped with protection circuits against static discharge.

Features

- High Speed: t_{PD} = 4.7 ns (Typ) at V_{CC} = 3.3 V
- Low Power Dissipation: I_{CC} = 4 μA (Max) at T_A = 25°C
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: V_{OLP} = 0.8 V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: Human Body Model > 2000 V;
  Machine Model > 200 V
- These Devices are Pb−Free and are RoHS Compliant

Application Notes

- Do not force a signal on an I/O pin when it is an active output, damage may occur
- All floating (high impedance) input or I/O pins must be fixed by means of pullup or pulldown resistors or bus terminator ICs
- A parasitic diode is formed between the bus and V_{CC} terminals. Therefore, the LVX245 cannot be used to interface 5.0 V to 3.0 V systems directly

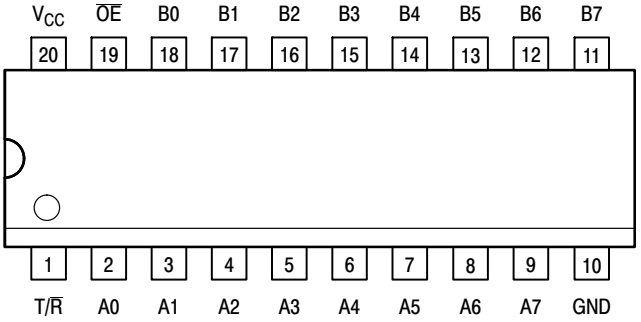

Figure 1. 20−Lead Pinout (Top View)

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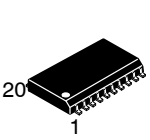
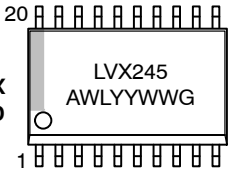
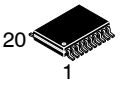
MARKING DIAGRAMS

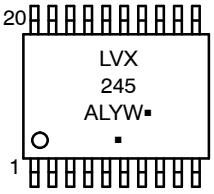


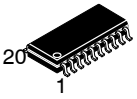
SOIC−20
DW SUFFIX
CASE 751D





TSSOP−20
DT SUFFIX
CASE 948E





SOEIAJ−20
M SUFFIX
CASE 967

LVX245	= Specific Device Code
A	= Assembly Location
WL, L	= Wafer Lot
Y	= Year
WW, W	= Work Week
G or ▪	= Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

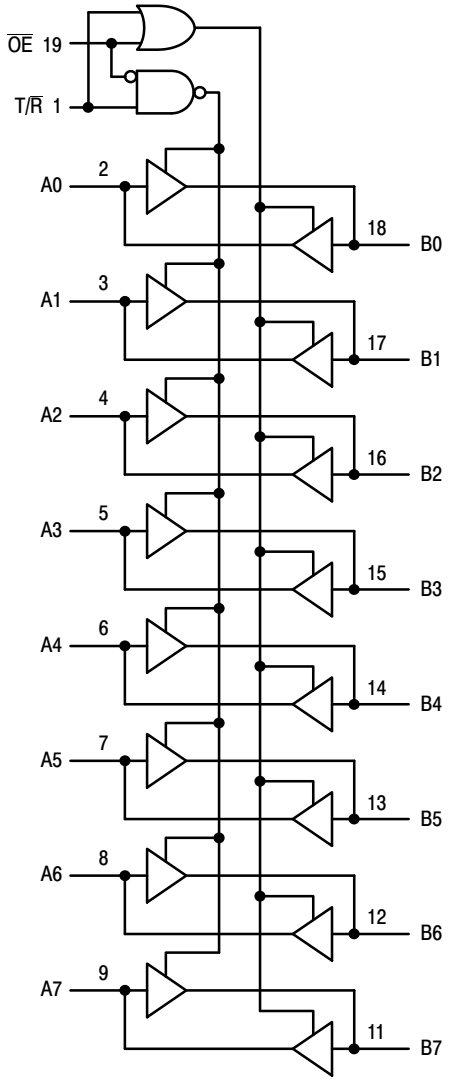


Figure 2. Logic Diagram

Table 1. PIN NAMES

Pins	Function
$\overline{OE}$	Output Enable Input
T/$\overline{R}$	Transmit/Receive Input
A0–A7	Side A 3–State Inputs or 3–State Outputs
Bo–B7	Side B 3–State Inputs or 3–State Outputs

INPUTS		OPERATING MODE Non–Inverting
OE	T/$\overline{R}$	
L	L	B Data to A Bus
L	H	A Data to B Bus
H	X	Z

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions are Acceptable; For I_{CC} reasons, Do Not Float Inputs

ORDERING INFORMATION

Device	Package	Shipping†
MC74LVX245DWR2G	SOIC–20 (Pb–Free)	1000 / Tape & Reel
MC74LVX245DTR2G	TSSOP–20*	2500 / Tape & Reel
MC74LVX245MG	SOEIAJ–20 (Pb–Free)	50 Units / Rail
MC74LVX245MELG	SOEIAJ–20 (Pb–Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	−0.5 to +7.0	V
V_{in}	DC Input Voltage (T/$\overline{R}$, $\overline{OE}$)	−0.5 to +7.0	V
$V_{I/O}$	DC Output Voltage	−0.5 to V_{CC} +0.5	V
I_{IK}	Input Diode Current	−20	mA
I_{OK}	Output Diode Current	±20	mA
I_{out}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±75	mA
P_D	Power Dissipation	180	mW
T_{stg}	Storage Temperature	−65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage	2.0	3.6	V
V_{in}	DC Input Voltage (T/$\overline{R}$, $\overline{OE}$)	0	5.5	V
$V_{I/O}$	DC Output Voltage	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	−40	+85	°C
$\Delta t/\Delta V$	Input Rise and Fall Time	0	100	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} V	T_A = 25°C			T_A = − 40 to 85°C		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	High−Level Input Voltage		2.0 3.0 3.6	1.5 2.0 2.4			1.5 2.0 2.4		V
V_{IL}	Low−Level Input Voltage		2.0 3.0 3.6			0.5 0.8 0.8		0.5 0.8 0.8	V
V_{OH}	High−Level Output Voltage (V_{in} = V_{IH} or V_{IL})	I_{OH} = −50 μA I_{OH} = −50 μA I_{OH} = −4 mA	2.0 3.0 3.0	1.9 2.9 2.58	2.0 3.0		1.9 2.9 2.48		V
V_{OL}	Low−Level Output Voltage (V_{in} = V_{IH} or V_{IL})	I_{OL} = 50 μA I_{OL} = 50 μA I_{OL} = 4 mA	2.0 3.0 3.0		0.0 0.0	0.1 0.1 0.36		0.1 0.1 0.44	V
I_{in}	Input Leakage Current	V_{in} = 5.5 V or GND (T/$\overline{R}$, $\overline{OE}$)	3.6			±0.1		±1.0	μA
I_{OZ}	Maximum 3−State Leakage Current	V_{in} = V_{IL} or V_{IH} V_{out} = V_{CC} or GND	3.6			±0.2 5		±2.5	μA
I_{CC}	Quiescent Supply Current	V_{in} = V_{CC} or GND	3.6			4.0		40.0	μA

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ ns)

Symbol	Parameter	Test Conditions		$T_A = 25°C$ Min	$T_A = 25°C$ Typ	$T_A = 25°C$ Max	$T_A = -40$ to $85°C$ Min	$T_A = -40$ to $85°C$ Max	Unit
t_{PLH}, t_{PHL}	Propagation Delay Input to Output	V_{CC} = 2.7 V	C_L = 15 pF		6.1	10.7	1.0	13.5	ns
			C_L = 50 pF		8.6	14.2	1.0	17.0	
		V_{CC} = 3.3 ± 0.3 V	C_L = 15 pF		4.7	6.6	1.0	8.0	
			C_L = 50 pF		7.2	10.1	1.0	11.5	
t_{PZL}, t_{PZH}	Output Enable Time to High and Low Level	V_{CC} = 2.7 V, R_L = 1 kΩ	C_L = 15 pF		9.0	16.9	1.0	20.5	ns
			C_L = 50 pF		11.5	20.4	1.0	24.0	
		V_{CC} = 3.3 ± 0.3 V, R_L = 1 kΩ	C_L = 15 pF		7.1	11.0	1.0	13.0	
			C_L = 50 pF		9.6	14.5	1.0	16.5	
t_{PLZ}, t_{PHZ}	Output Disable Time From High and Low Level	V_{CC} = 2.7 V, R_L = 1 kΩ	C_L = 50 pF		11.5	18.0	1.0	21.0	ns
		V_{CC} = 3.3 ± 0.3 V, R_L = 1 kΩ	C_L = 50 pF		9.6	12.8	1.0	14.5	
t_{OSHL} t_{OSLH}	Output−to−Output Skew (Note 1)	V_{CC} = 2.7 V	C_L = 50 pF			1.5		1.5	ns
		V_{CC} = 3.3 ±0.3 V	C_L = 50 pF			1.5		1.5	

1. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH−to−LOW (t_{OSHL}) or LOW−to−HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	$T_A = 25°C$ Min	$T_A = 25°C$ Typ	$T_A = 25°C$ Max	$T_A = -40$ to $85°C$ Min	$T_A = -40$ to $85°C$ Max	Unit
C_{in}	Input Capacitance ($T/\overline{R}$, $\overline{OE}$)		4	10		10	pF
$C_{I/O}$	Maximum 3−State I/O Capacitance		8				pF
C_{PD}	Power Dissipation Capacitance (Note 2)		21				pF

2. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}/8$ (per bit). C_{PD} is used to determine the no−load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

NOISE CHARACTERISTICS (Input $t_r = t_f = 3.0$ns, $C_L = 50$pF, $V_{CC} = 3.3$V, Measured in SOIC Package)

Symbol	Characteristic	$T_A = 25°C$ Typ	$T_A = 25°C$ Max	Unit
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	0.5	0.8	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	−0.5	−0.8	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		2.0	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		0.8	V

SWITCHING WAVEFORMS

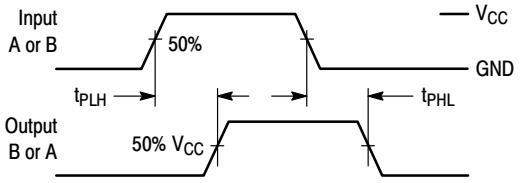


Figure 3.

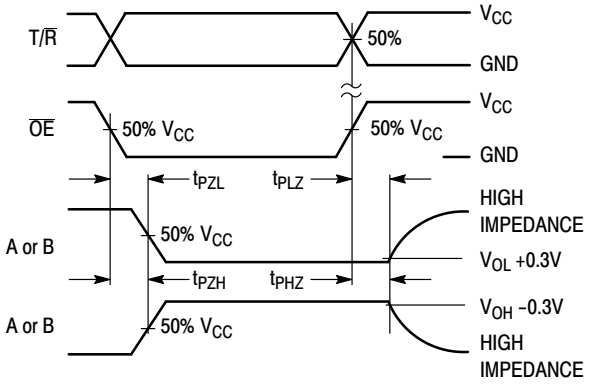
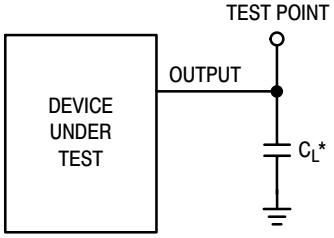


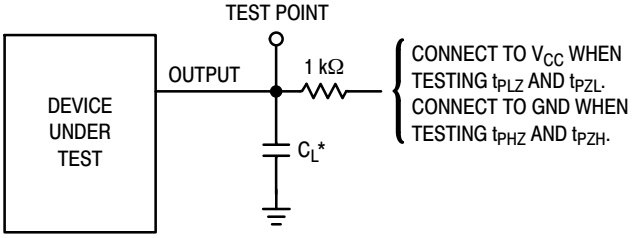
Figure 4.

TEST CIRCUITS



*Includes all probe and jig capacitance

Figure 5. Propagation Delay Test Circuit

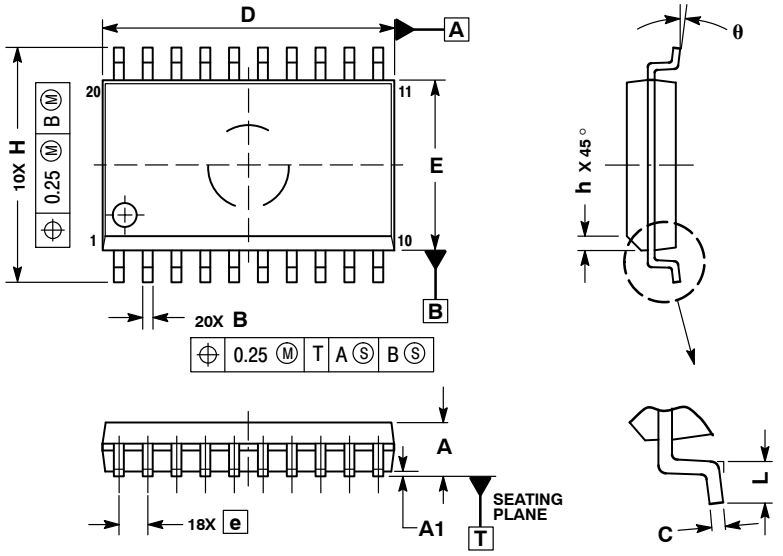


*Includes all probe and jig capacitance

Figure 6. 3−State Test Circuit

PACKAGE DIMENSIONS

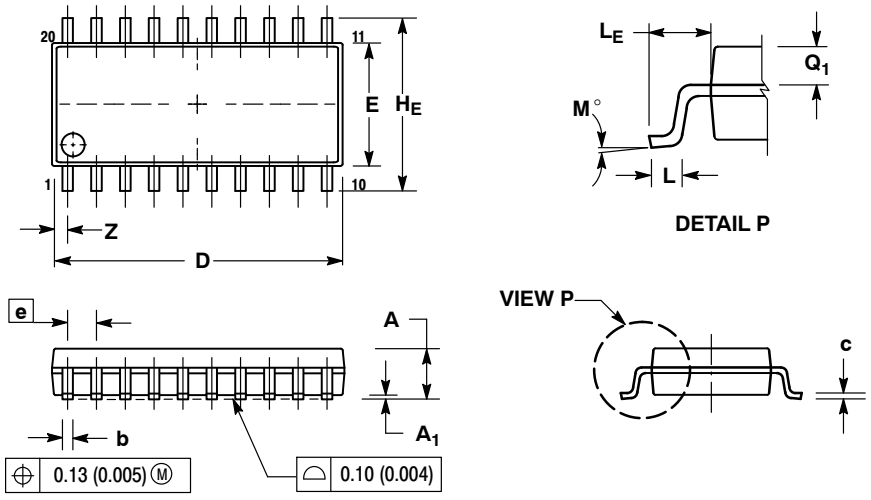
SOIC−20
CASE 751D−05
ISSUE G



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

SOEIAJ−20
CASE 967−01
ISSUE A

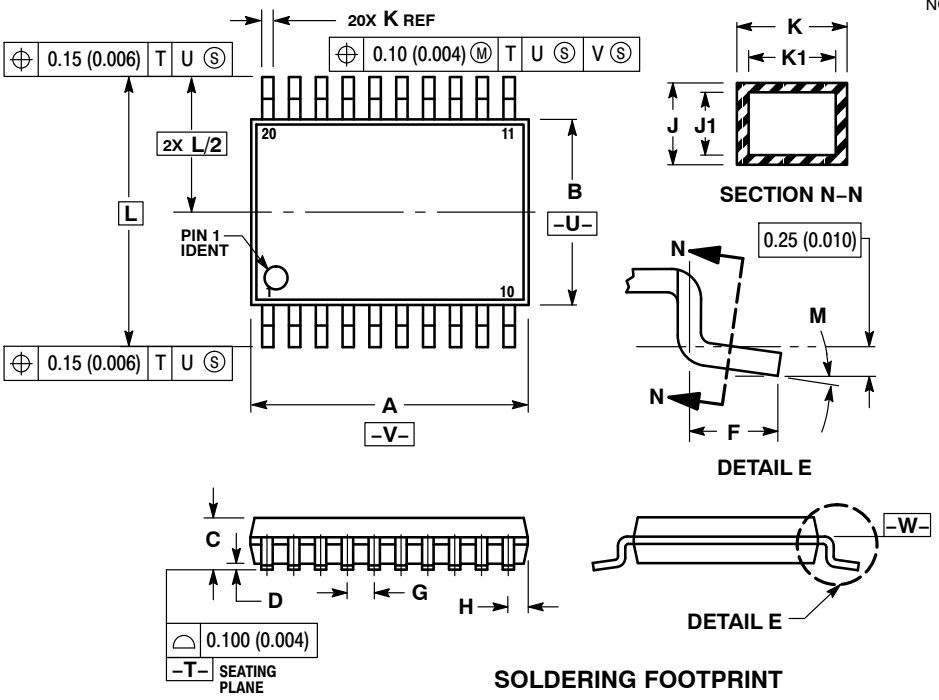


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q_1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

PACKAGE DIMENSIONS

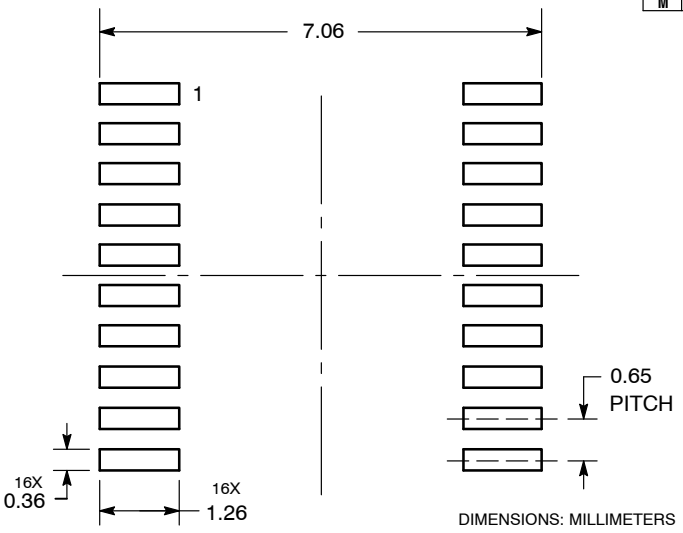
TSSOP−20
CASE 948E−02
ISSUE C



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

PUBLICATION ORDERING INFORMATION

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